

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

GBU15005-MS THRU GBU1510-MS

Product specification

VOLTAGE RANGE: 50 - 1000V
CURRENT: 15 A

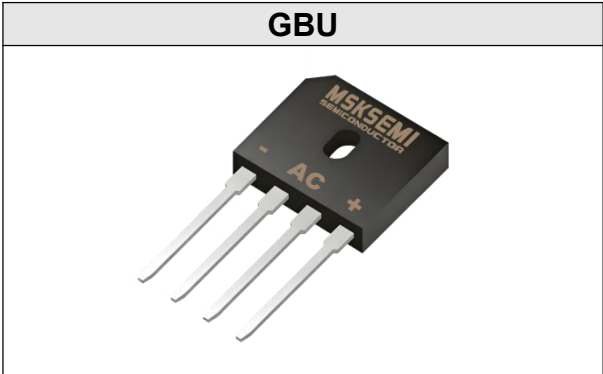
FEATURES

- Surge overload rating -230 amperes peak
- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- Plastic material has U/L lammability classification 94V-0

MECHANICAL DATA

- **Case** : JEDEC GBU Molded plastic body
- **Terminals** : Solder plated, solderable per MIL-STD-750,Method 2026
- **Polarity** : Polarity symbol marking on body
- **Mounting Position**: Any

REFERENCE NEWS



Marking

GBU 15005-MS	GBU 1501-MS	GBU 1502-MS	GBU 1504-MS
GBU1506-MS	GBU1508-MS	GBU1510-MS	

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	GBU15005-MS	GBU1501-MS	GBU1502-MS	GBU1504-MS	GBU1506-MS	GBU1508-MS	GBU1510-MS	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward (with heatsink NOTE 2) Rectified current @ $T_c = 100^\circ\text{C}$ (without heatsink)	I_{AV}	15.0 3.2							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	230							A
Rating for Fusing ($t < 8.3\text{ms}$)	I_t	219							A's
Maximum forward voltage at 7.5A DC	V_F	1.1							V
Maximum DC reverse current at rated DC blocking voltage $T_A = 25^\circ\text{C}$ $T_A = 125^\circ\text{C}$	I_R	5							μA
		0.5							mA
Typical Junction Capacitance (Note 1)	C_J	70							pF
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	2.2							$^\circ\text{C/W}$
Operating junction temperature range	T_J	-55 to +150							$^\circ\text{C}$
storage temperature range	T_{STG}	-55 to +150							$^\circ\text{C}$

NOTES:

1. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
2. Device mounted on 100mm*100mm*1.6mm cu plate heatsink.
3. The typical data above is for reference only

RATING AND CHARACTERISTIC CURVES (GBU15005-MS THRU GBU1510-MS)

FIG.1-DERATING CURVE FOR
OUTPUT RECTIFIED CURRENT

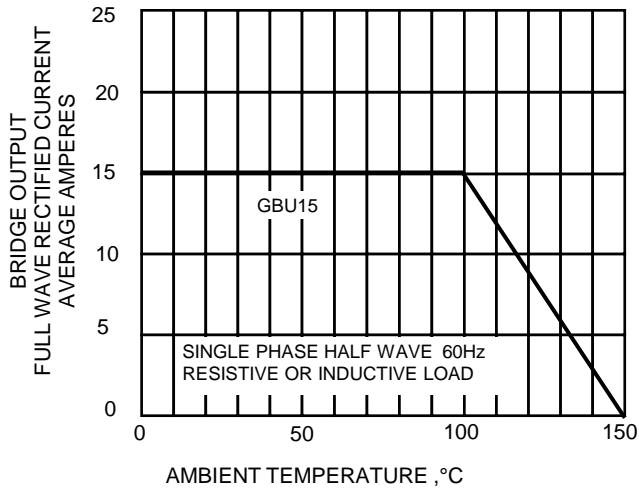


FIG.2-MAXIMUM NON-REPETITIVE SURGE CURRENT

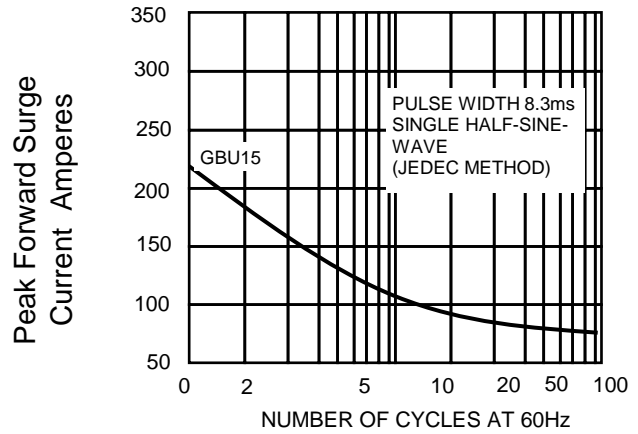


FIG.3-TYPICAL REVERSE
CHARACTERISTICS

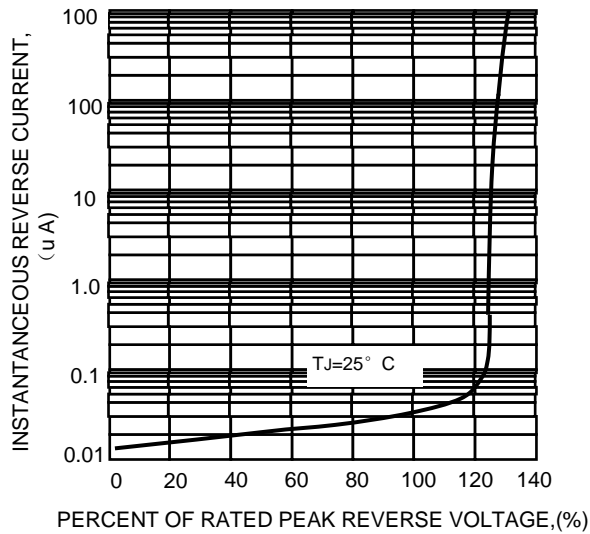
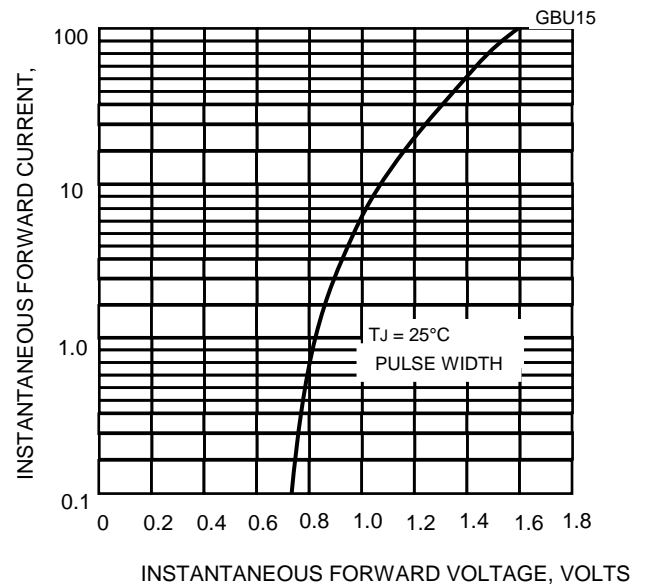
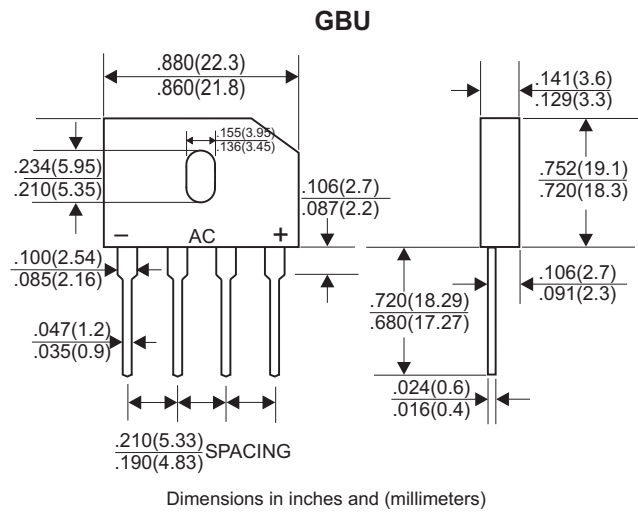


FIG.4-TYPICAL FORWARD CHARACTERISTICS



PACKAGE MECHANICAL DATA



REEL SPECIFICATION

P/N	PKG	QTY
GBU15005-MS THRU GBU1510-MS	GBU	500

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